### **COMPONENT SPECIFICATION**

版次:第3版 MAX ECHO

N	Ferrite Chip EMI Suppressors	COMP	OSITE SPECIFICATION	1/
M E	EBMS-100505	SPEC#	EBMS100505A121 0.5A	8

#### 1. SCOPE

This specification applies to the EBMS-1005 series Ferrite Chip EMI suppressors.

#### 2. STANDARD ATMOSPHERIC CONDITIONS

Unless otherwise specified the standard range of atmospheric conditions for making measurements and tests is as follows:

Ambient temperature : 20±15°C Relative humidity : 30~70%

If there may be any doubt on the results, measurements shall be made within

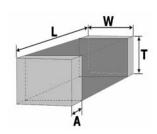
the following limits:

Ambient temperature : 25±5°C Relative humidity : 30~70%

3. RATINGS

PART NO	IMPEDANCE ( $\Omega$ )	DC RESISTANCE	RATED CURRENT
FART NO	AT 100 MHz 500mV	$(\Omega)$ Max	(mA) Max
EBMS100505A121 0.5A	120±25%	0.25	500

### 4. DIMENSION



OPERATING TEMP. RANGE:  $-55^{\circ}$ C ~  $+125^{\circ}$ C STORAGE TEMP. RANGE:  $-10^{\circ}$ C ~  $+40^{\circ}$ C

TYPE	Ц	W	T	Α
EBMS-1005	1.0±0.05	0.5±0.05	0.5±0.05	0.1~0.3
LDIVIO-1003	(.039±.002)	(.020±.002)	(.020±.002)	

# 5. The place of origin:

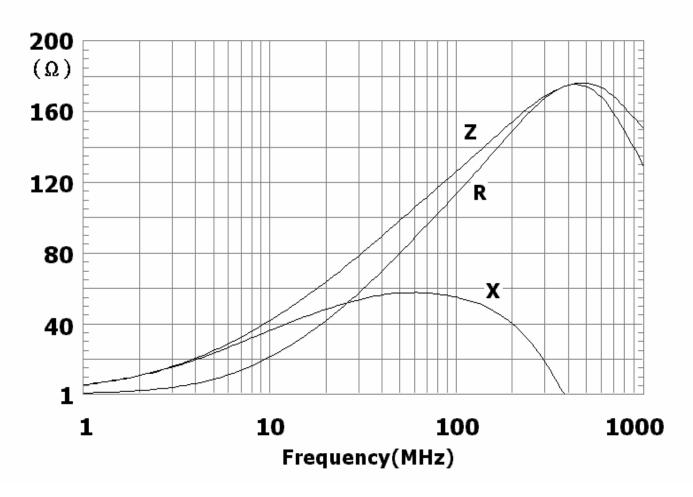
Taichung, Taiwan

HISTORY	DATE		SIGN.	SIGN.	
PLANNED BY	CHECKED BY	APPROVED BY			
JSHING	esu	Chi Chi Huang	鈺鎧文件中心 發行章		

# MAX ECHO 鈺鎧科技股份有限公司規格標準書 COMPONENT SPECIFICATION

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# EBMS100505A121 0.5A



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### **COMPONENT SPECIFICATION**

版次:第3版 MAX ECHO Ferrite Chip EMI Suppressors COMPOSITE SPECIFICATION Α

EBMS-100505

SPEC# EBMS100505A121 0.5A

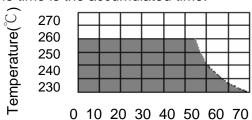
6) Reflow soldering conditions

M

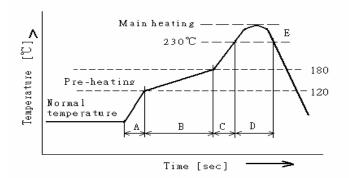
• Pre—heating should be in such a way that the temperature difference between solder and ferrite surface is limited to 150°C max.Also cooling into solvent after soldering should be in such a way that the temperature difference is limited to 100°C max.

Unenough pre—heating may cause cracks on the ferrite, resulting in the deterioration of product quality.

 Products should be soldered within the following allowable range indicated by the slanted line. The excessive soldering conditions may cause the corrosion of the electrode, When soldering is repeated, allowable time is the accumulated time.



#### Temperature Profile



Α	Slope of temp. rise	1 to 5	• • •	°C/sec
В	Heat time	50 to 150		sec
Ь	Heat temperature	120 to 180		$^{\circ}\mathbb{C}$
С	Slope of temp. rise	1 to 5		°C/sec
D	Time over 230 $^{\circ}$ C	90~120		sec
Е	Peak temperature	255~260		$^{\circ}\mathbb{C}$
E	Peak hold time	10 max.		sec
	No. of mounting	3		times

(Melting area of solder)

6-1 Reworking with soldering iron

· · · · · · · · · · · · · · · · · · ·	
Preheating	150°C, Iminute
Tip temperature	280°C max
Soldering time	3seconds max.
Soldering iron output	30w max.
End of soldering iron	∮ 3mm max.

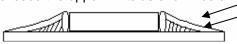
• Reworking should be limited to only one time.

Note: Do not directly touch the products with the tip of the soldering iron in order to prevent the crack on the ferrite material due to the thermal shock.

6-2 Solder Volume

Solder shall be used not to be exceed the upper limits as shown below.

**Upper Limit** Recommendable



Accordingly increasing the solder volume, the mechanical stress to product is also increased. Exceeding solder volume may cause the failure of mechanical or electrical performance.

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#### **7 EQUIPMENT**

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#### 7-1 IMPEDANCE

Impedance shall be measured with HP-4286A impedance analyzer or equivalent system

### 7-2 DC RESISTANCE

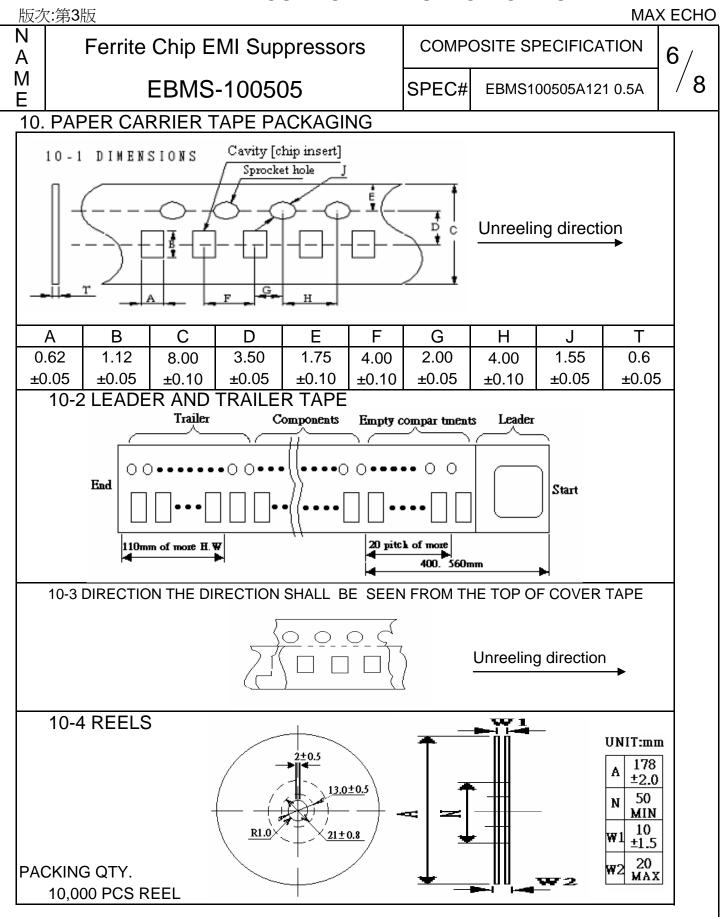
DC resistance shall be measured using HP 4338 digital mili — ohm meter with 4 terminal method.

### 8.MECHANICAL CHARACTERISTICS

	CAL CHARACTERISTICS	TEOT CONDITIONS
ITEM	Specification	TEST CONDITIONS
TERMINAL	Without deformation cases	Solder chip on PCB and applied 10N
STRENGTH	impedance shall be satisfied ± 30%	(1.02Kgf) for 10 sec
	DC resistance shall be satisfied.	CHIP BEAD
		F
Substrate	Without deformation cases,	After soldering a chip to a test substrate,
bending test	impedance shall be satisfied ± 30%	bend the substrate by 3mm hold for 10s
	DC resistance shall be satisfied.	and then return.
		Soldering shall be done in accordance
		with the recommended PC board pattern
		and reflow soldering.
		unit : mm  45 45 45 100
RESISTANCE	No visible damage	Solder Temp. : 265±3℃
TO SOLDER	Electrical characteristics and mechanic	Immersion time : 6±1 sec
HEAT	characteristics shall be satisfied.	Preheating : $100^{\circ}$ to $150^{\circ}$ , 1 minute.
		Measurement to be made after keeping at room
	Consult standard MIL-STD-202	temp for 24±2 hrs.
	METHOD 210	Solder : Sn-3Ag-0.5Cu
SOLDER-	95% min. coverage of all	Solder temp. : 240 $\pm$ 5 $^{\circ}$ C
ABILITY	metabolised area	Immersion time : 3±1 sec
		Solder : Sn-3Ag-0.5Cu
	Consult standard J-STD-002	

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N A	Ferrite Chip EMI Suppressors	COMPOSITE	E SPECIFICATION	5/
M	EBMS-100505	SPEC# EB	MS100505A121 0.5A	8
E	EBMS-100505  RELIABILITY AND TEST CONDITIONS 9-1 HIGH TEMPERATURE RESISTANCE a. Performance specification 1.Appearance: no mechanical damage 2.Impedance shall be with ±30% of the ir 3. DC resistance shall be satisfied b.Test condition 1.Temperature125℃±2℃ 2.Applied current: Rated current(maxim 3.Testing time: 1008±12hrs 4.Measurement: After placing at room a 9-2 HUMIDITY RESISTANCE a.Performance specification 1.Appearance: no mechanical damage 2.Impedance:within ±30% of initial value 3.DC resistance shall be satisfied b.Test condition 1.Humidity: 90 to 95% RH 2.Temperature: 60+2°℃ 3.Applied current: Rated current (maxin 4.Testing time: 1008±12hours 5.Measurement: After placing at room a 9-3 TEMPERATURE CYCLE a.Performance specification 1.Appearance: no mechanical damage 2.Impedance:within ±30% of initial value 3. DC resistance shall be satisfied b.Test condition 1.Temperature-55℃,+125℃ kept stabili 2.Cycle: 100 cycles 3.Measurement: After placing for 24 ho 4. step155℃ temp±3℃ 30±3 minutes step2. Standard atmospheric conditi step3. +125℃ temp±2℃ 30±3 minutes step2. Standard atmospheric conditi step3. +125℃ temp±2℃ 30±3 minutes step4. Standard atmospheric conditi step3. +125℃ temp±2℃ 30±3 minutes step2. Standard atmospheric conditi step3. +125℃ temp±2℃ 30±3 minutes step2. Standard atmospheric conditi step3. +125℃ temp±2℃ 30±3 minutes step2. Standard atmospheric conditi step3. +125℃ temp±2℃ 30±3 minutes step2. Standard atmospheric conditi step3. +125℃ temp±2℃ 30±3 minutes step2. Standard atmospheric conditi step3. +125℃ temp±2℃ 30±3 minutes step2. Standard atmospheric conditi step3. +125℃ temp±2℃ 30±3 minutes step2. Standard atmospheric conditi step3. +125℃ temp±2℃ 30±3 minutes step2. Standard atmospheric conditi step3. +125℃ temp±2℃ 30±3 minutes step2. Standard atmospheric conditi step3. +125℃ temp±3℃ 30±3 minutes step2. Standard atmospheric conditi step3. +125℃ temp±3℃ 30±3 minutes step2. Standard atmospheric conditi step3. +125℃ temp±3℃ 30±3 minutes step4. Standard atmospheric conditi step3. +125℃ temp±3℃ 3	itial value  um value) mbient tempera  zed for 30 minu urs minimum at ons 5s or less tes ons 5s or less EST  itial value  urs minimum at itial value zed for 30 minu rs minimum at	ature for 24 hours minutes each troom ambient temperatures each	nimum

### **COMPONENT SPECIFICATION**



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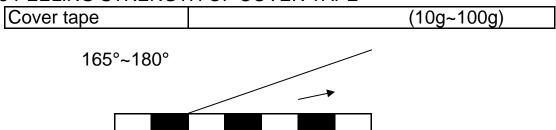
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N A Ferrite Chip EMI Suppressors COMPOSITE SPECIFICATION 7/8

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#### 10-5 PEELING STRENGTH OF COVER TAPE



Test condition

1) peel angle: 165°~180° vs carrier tape

2) peel speed: 300mm/min

11.PACKAGING

1) Tape & Reel packaging in composite specification 6/8

2) Reel and a bag of desiccant shall be packed in Nylon or plastic bag

3) Maximum of 5 bags shall be packaged in a inner box

4) Maximum of 6 inner box shall be packaged in a outer box

12.Reel Label

Producing the goods label needs to indicate (1) Pb Free (2) RoHS Compliant

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#### 13. STORAGE

- 13-1The solderability of the external electrode may be deteriorated if packages are stored where they are exposed to high humidity. Packages must be stored at 40°C or less and 70% RH or less.
- 13-2 The solderability of the external electrode may be deteriorated if packages are stored where they are exposed to dust or harmful gas (hydrogen chloride, sulfurous acid gas or hydrogen sulfide).
- 13-3 Packaging material may be deformed if packages are stored where they are exposed to heat or direct sun—light.
- 13-4 Minimum packages, such as polyvinyl heat—seal packages shall not be opened until just before they are used. If opened, use the reels as soon as possible.
- 13-5 Solderability specified in composite specification 4/8 shall be for 6 months from the date of delivery on condition that they are stored at the environment specified clause 13-1 & 13-2.

For those parts which passed more than 6 months shall be checked solderability before it is used.